MINED BY :		FILE NO . CAS-51580
Yung Chang Hu	EMERGING DISPLAY	ISSUE : APR.04, 2007
OVED BY:	TECHNOLOGIES CORPORATION	TOTAL PAGE : 22
David Chang		VERSION : 1
CUSTOMER	ACCEPTANCE SPEC	CIFICATIONS
МО	DEL NO.: E T 0 2 0 0 0 3 D M U	
FOR CUSTOMER'S APPROV. DATE :	(RoHS) MESSRS : AL	
FOR CUSTOMER'S APPROV DATE : BY :	(RoHS) MESSRS : AL	



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			<u> </u>	
1. GENERAL SPECIFICATIONS				
1.1 APPLICATION NOTES FOR PLEASE REFER TO :	CONTROLL	ER/DRIVER		
ILITEK I	L I 9 2 2 1 / I L	19222		
1.2 MATERIAL SAFETY DESCR ASSEMBLIES SHALL COMP INCLUDING PROHIBITED M MERCURY, CADMIUM, HEX BIPHENYLS (PBB) AND POL DIPHENYL ETHERS (PBDE)	IPTION LY WITH EUF ATERIALS/CO AVALENT C YBROMINAT	ROPEAN ROHS RE OMPONENTS CON HROMIUM, POLYH 'ED	QUIREME TAINING 3ROMINA	NTS, LEAD, TED
2 MECHANICAL SPECIFICATION	IS			
(1) DISPLAY SIZE (inch)		2.0"		
(2) NUMBER OF DOTS		176W * (RGB) * 220H	DOTS	
(3) MODULE SIZE		38 18W * 53 32H * 3 1	(D) mm	
		(WITHOUT FPC)	(_)	
(4) ACTIVE AREA		31.68W * 39.6H mm (	LCD)	
(5) DOT SIZE		0.06W * 0.18H mm	,	
(6) PIXEL SIZE		0.18W * 0.18H mm		
(7) LCD TYPE		TFT, TRANSMISSIV	E	
(8) COLOR		262K (18BIT)		
(9) VIEWING DIRECTION		12 O'CLOCK		
(10) BACK LIGHT		LED . COLOR : WHIT	Έ	
		,		



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#### 3. ABSOLUTE MAXIMUM RATINGS

#### 3.1 ELECTRICAL ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	REMARK
	VCC	-0.3	4.6	V	
POWER SUPPLY FOR LOGIC	IOVCC	-0.3	4.6	V	
	VCI	-0.3	4.6	V	
INPUT VOLTAGE	VI	- 0.3	VCC+0.3	V	
STATIC ELECTRICITY				V	NOTE (1)

NOTE(1) : LCM SHOULD BE GROUNDED DURING HANDING LCM.

#### 3.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS.

ITEM	OPERATING		STORAGE		DEMADV	
	MIN.	MAX.	MIN.	MAX.	KEWIAKK	
AMBIENT TEMPERATURE	- 20°C	70°C	- 30°C	80°C	NOTE (2), (3)	
HUMIDITY	ΝΟΤΙ	E(A)	NOT	E(A)	WITHOUT	
	NOT	C(4)	NOT	C(4)	CONDENSATION	
VIBRATION		2.45m/S <sup>2</sup> ( 0.25G)		11.76m/S <sup>2</sup> (1.2G)	5~20Hz , 1HR 20~500Hz(20Hz), 1HR 20~500Hz(500Hz), 1HR X,Y,Z, TOTAL 3HR	
SHOCK		29.4m/S <sup>2</sup> (3G)		490m/S <sup>2</sup> (50G)	10 m SECONDS XYZ DIRECTIONS 1 TIME EACH	
CORROSIVE GAS	NOT ACC	EPTABLE	NOT ACC	EPTABLE		

NOTE (2) : Ta AT  $-30^{\circ}C$ : 48HR MAX.

80°C: 48HR MAX.

NOTE (3) : BACKGROUND COLOR CHANGES SLIGHTLY DEPENDING ON AMBIENT TEMPERATURE THIS PHENOMENON IS REVERSIBLE.

NOTE (4) : Ta  $\leq 60^{\circ}$ C : 90%HR MAX.

Ta > 60°C : ABSOLUTE HUMIDITY MUST BE LOWER THAN THE HUMIDITY OF 90%RH AT 60°C.



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#### 4. ELECTRICAL CHARACTERISTICS

							$Ta = 25  {}^{\circ}C$
PARAMETER	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REMARK
INPUT POWER SUPPLY	VCC	—	2.5	2.8	3.3	V	
INTERNAL REFERENCE VOLTAGE	VCI		2.5	2.8	3.3	V	
INTERNAL SIGNAL VOLTAGE	IOVCC	_	2.5	2.8	3.3	V	
INPUT VOLTAGE	$V_{\mathrm{IH}}$	H LEVEL	0.8VCC		VCC	V	
NOTE (1)	V <sub>IL</sub>	L LEVEL	-0.3	_	0.2VCC	V	
OUTPUT VOLTAGE	V <sub>OH</sub>	H LEVEL	0.8VCC			V	
NOTE (1)	V <sub>OL</sub>	L LEVEL			0.2VCC	V	
OUTPUT CURRENT NOTE (2)	IC			(4)	(6)	mA	
VOLTAGE OF B/L	VF	IF=(40 mA)		(3.3)	(4.0)	V	

NOTE (1): APPLIED TO TERMINALS, NRESET, VSYNC, HSYNC, DOTCLK, ENABLE, R5~R0,  $G5\sim G0, B5\sim B0, SDO, SDI, NCS$ NOTE (2): IC: Ivcc + Ivci + Iiovcc



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# 5. OPTICAL CHARACTERISTICS (NOTE1)

Ta = 25 °C

ITE	М	SYMBOL	COND	ITION	MIN.	TYP.	MAX.	UNIT	REMARK
		θy+		$\Omega_{\rm r} = 0^{\circ}$	(55)	(60)			
		θу-	CP > 10	$\Theta x = 0$	(15)	(20)		dag	
VIEWING ANOL	<sup>2</sup> E	θx-	$CK \ge 10$	$0 = 0^{\circ}$	(40)	(45)		ueg.	
		$\theta x +$		0y - 0	(40)	(45)			
CONTRAST RAT	Ю	CR	$\theta \mathbf{x} = \theta$	$y = 0^{\circ}$	150	200			
DESDONSE TIM	C	tr(rise)	$\theta_{\rm v} = 0$	$v = 0^{\circ}$		(12)	(16)	msaa	
RESPONSE TIME		tf(fall)	$\theta x = \theta y = 0^{\circ}$			(18)	(24)	liisec	
THE BRIGHTNES OF MODULE	SS	В	$\theta x = \theta y = 0^{\circ}$		200	250		cd/m <sub>2</sub>	—
	WILLTE	Х		(		(0.310)	(0.330)		
	WHILE	Y			(0.312)	(0.341)	(0.361)		
COLOB OF	DED	Х	VIEV	VING	(0.635)	(0.655)	(0.675)		
CULOK OF	KED	Y	NORMAI	L AUNLE	(0.309)	(0.329)	(0.349)		
COORDINATE	GREEN	Х	$\theta x =$	= 0°	(0.292)	(0.312)	(0.332)		
COORDINATE	UKEEN	Y	θy =	= 0°	(0.555)	(0.575)	(0.595)		
	DITE	Х			(0.114)	(0.134)	(0.154)		
	DLUE	Y				(0.135)	(0.155)		
THE BRIGHTNESS OF UNIFORMITY			IF =(4	40 mA)	(70)	(75)		%	NOTE(1)

NOTE (1): THE BRIGHTNESS UNIFORMITY CALCULATE METHOD

 $\left[1 - \frac{(MAXIMUN - MINIMUN)}{AVERAGE}\right] \times 100\%$ 















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0 INI7	FEREACE SI	GNAIS			
<i>9</i> . IN	TERFACE SI				
PIN NO	SYMBOL		FUNCTION		
1	NC	NOT CONNEC	CTED		
2	nRESET	RESET			
3	VSYNC	FRAME SYNC	CHRONIZING SIGNAL		
4	HSYNC	LINC SYNCH	RONIZING SIGNAL		
5	DOTLCK	DOT CLOCK			
6	ENABLE	DATA ENABL	ĿE		
7	NC	NOT CONNEC	CTED		
8	R5	DATA BUS			
9	R4	DATA BUS			
10	R3	DATA BUS			
11	R2	DATA BUS			
12	R1	DATA BUS			
13	R0	DATA BUS			
14	G5	DATA BUS			
15	G4	DATA BUS			
16	G3	DATA BUS			
17	G2	DATA BUS			
18	G1	DATA BUS			
19	G0	DATA BUS			
20	B5	DATA BUS			
21	B4	DATA BUS			
22	B3	DATA BUS			
23	B2	DATA BUS			
24	 B1	DATA BUS			
25	BO				
23		DATA DUS			
26		NOT CONNEC			
27	SDU	SERIAL INST			
28	<u>SDI</u>	SER IAL INST			
29	NC	NOT CONNEC	CTED		
30	SCL	SERIAL CLOC			
31	NC	NOT CONNEC	CTED		
32	nCS	CHIP SELECT	SIGNAL		
33	VCC	POWER SUPP	LY FOR LOGIC		
34	IOVCC	POWER SUPP	LY FOR INTERFACE SIGNAL		
35	VCI	POWER SUPP	LY FOR ANALOG		
36	GND	GROUND			
37	VLED_A	LED BACKLIC	GHT POWER (A)		
38	LED_K1	LED BACKLIC	GHT POWER (K1)		
39	LED K2	LED BACKLIC	GHT POWER (K2)		



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10. POWER SUPPLY 10.1 POWER SUPPLY FOR LCM	1		
IOVCC —			
LCM VCI VCC	2.8V 2.8V	2.8V	
vss —		-	
1 0 .2 POWER SUPPLY FOR LCM	I BACKLIGHT		
A		.3V)	
K1 < K2 <	• (4	0)IIIA	



EMERGING	DISPLAY	MODEL NO.	VERSION	PAGE
TECHNOLOGIE	S CORPORATION	E T 0 2 0 0 0 3 D M U (RoHS)	1	10
11. SPECIFIC 11.1 APP THIS DELI	ATION OF AUDACIT LICATION INSPECTION STANDA VERED FROM EMERG	Y ASSURANCE ARD IS TO BE APPLIED TO THE FING DISPLAY TECHNOLOGIES	LCD MOI CORP.( E	DULE .D.T)
TO C	USTOMERS			
11.2 INSF	PECTION CONDITIONS	5		
11.2.1	ENVIRONMENTAL C ROOM TEMPERATUR HUMIDITY : 50 ± 10%	ONDITIONS RE : 25°C ± 5°C 5 RH		
11.2.2	DISPLAY-ON INSPEC SCREEN THE DISTANCE BETY EYES SHALL BE AT I ONE FLUORESCENT	TION, VISUAL APPEARANCE II WEEN THE MODULE AND THE LEAST 30cm UNDER ILLUMINA LAMP OF 20W.	NSPECTIC INSPECTO TION OF	)N ON OR'S
11.2.3	INSPECTION LOT QUANTITY PER DEL	IVERY LOT FOR EACH MODEL		
11.2.4	INSPECTION METHO A SAMPLING INSPEC FOLLOWING PROVIS (a)APPLICABLE STAN (b)AQL : MAJOR DEF MINOR DEF TOTAL DEF	D CTION SHALL BE MADE ACCOR SIONS TO JUDGE THE ACCEPTA NDARD : MIL-STD-105E NORMAL INSPECTION, SINGLI LEVEL II ECT : AQL 0.65 ECT : AQL 2.5 ECTS : AQL 2.5	tDING TO ABILITY E SAMPLI	THE NG











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TECHNOLOGIES C	ORPORATION	E T 0 2 0 0 0 3 D M U (RoHS)	1	13
11.5 INSPECT	FION STANDARDS			
11.5.1 VI	SUAL DEFECTS CLA	ASSIFICATION		
TYPE OF DEFECT	INSPECTION ITEM	M DEFECT FEATUR	E	AQL
	1.DISPLAY ON	• DEFECT TO MISS SPECIF DISPLAY FUNCTION, FO AND SPECIFIED DOTS EX : DISCONNECTION, S CIRCUIT ETC	IED DR ALL SHORT	
MAJOR DEFECT	2.BACKLIGHT	<ul> <li>NO LIGHT</li> <li>FLICKERING AND OTHER ABNORMAL ILLUMINATION</li> </ul>		0.65
	3.DIMENSIONS	SUBJECT TO INDIVIDUAL ACCEPTANCE SPECIFICATIONS		
	1.DISPLAY ZONE	<ul> <li>BLACK/WHITE SPOT</li> <li>BUBBLES ON POLARIZEF</li> <li>BLACK/WHITE LINE</li> <li>SCRATCH</li> <li>CONTAMINATION</li> <li>LEVER COLOR SPREED</li> </ul>	ξ	
	2.BEZEL ZONE	STAINS     SCRATCHES     FOREIGN MATTER		
	3.PCB	• CRACKS • SCRATCHES • STAINS		2.5
	4.SOLDERING	<ul> <li>INSUFFICIENT SOLDER</li> <li>SOLDERED IN INCORRECT POSITION</li> <li>CONVEX SOLDERING SPACE</li> <li>SOLDER BALLS</li> <li>SOLDER SCRAPS</li> <li>LIGHT LINE</li> </ul>	CT OT	
	(ALL ON)	• LIONI LINE		



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Т	FECHNOLOGIES CORI	PORATION	ЕТ(	0 2 0 0 0 3 D M U (	RoHS)	1	14
	11.5.2 INSPECATION CRITERION						
N	O. ITEM			CRITERIA			
1	1. DISPLAY ON INSPECTION	(1)INCORRE (2)MISSING (3)DIM SEGN (4)OPERATI	<ul> <li>(1)INCORRECT PATTERN</li> <li>(2)MISSING SEGMENT</li> <li>(3)DIM SEGMENT</li> <li>(4)OPERATING VOLTAGE BEYOND SPEC</li> </ul>				
2	2. OVERALL DIMENSIONS	(1)OVERALL DIMENSION BEYOND SPEC					
	(1)INSPECTION PATTERN : FULL WHITE,FULL BLACK,RED,GREEN AND BLUE SCREENS. (2)						
			BRIGH	IT DOT		N≤3	
			DARK	DOT		N≤3	
			TOTAL	DOT		N≤3	
	BLACK SPOT I	DOT	MININ BETW	EEN BRIGHT DOTS		L≥5mm	
3	3. WHITE SPOT I ON-DISPLAY	DEFECT MINIMUM DISTANCE BETWEEN BRIGHT DOTS AND L≥5mm DARK DOTS					
	MINIMUM DISTANCE BETWEEN DARK DOTS L≥5mm						
	NOTE : THE DEFINITION OF DOT DEFECT: THE DOT						
	DEFECT WAS JUDGED AFTER REPAIR AND THE SIZE						
	OF A DEFECTIVE DOT OVER 1/2 OF WHOLE DOT IS						
		KEGARI	JED A	S UNE DEFECTIV	E DOT.		
		(1) THE FOLI		NG BLACK LINE ,	WHILE	LINE AKE	(
				LEWING AREA .			
	BLACK LINE	UENCT		WIDTU · W	DEDMI	CODIE N	
4	4. WHITE LINE		11.L 5	WIDITI.W		NUDE	<u>U.</u>
	ON-DISPLAY	$L \ge 0$		$W \ge 0.1$			—
		$0.3 \le L$	<u> </u>	$0.1 \le W \le 0.3$			_
	$3 < L$ $0.5 \le W$ NONE						



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		1	Ľ	LNITENIA			
5.	BUBBLES OF POLARIZER /SURFACE STAINS /DIRT/CF FAIL /SPOT	BUBBLE ON THE POLARIZER SURFA CF FA NOTE : (1)PC AP PO AC (2)TH BE (3)TH AS	LINE SHAPE L:LENGTH(mm) DOT SHAPE D:AVERAGE DIAMETER(mm) CE STATUS AIL / SPOT DLARIZER BUBBI PEARS ON ACTIV LARIZER BUBBL TIVE DISPLAY A HE EXTRANEOUS OBSERVED WHH HE DEFINITION C FOLLOWING. AVERAGE DIAM	L $\leq$ 0.5, W $\leq$ 0.1 0.5 < L $\leq$ 3 0.1 < W $\leq$ 0.5 D $\leq$ 0.25 0.25 < D $\leq$ 0.5 0.5 < D D < 0.1 mm 0.1 < D $\leq$ 0.3mm LE IS DEFINED AS T VE DISPLAY AREA. E SHALL BE IGNOR E APPEARS ON THE REA. S SUBSTANCE IS DE EN THE MODULE IS DF AVERAGE DIAMI ETER(D)=(X+Y)/2, V X	LGNORE $N \le 2$ LGNORE $N \le 5$ NOTEIGNORE $N \le 3$ IGNORE $N \le 3$ THE BUBBLETHE DEFECT OFED IF THEOUTSIDE OFEFINED AS IT CANPOWER ON.ETER ,D IS DEFINEDWHERE		
6.	SCRATCHES AND DENT ON GLASS POLARIZER	(1) PLS REFER TO THE ABOVE NO.3 AND 4 TO DETERMINE SCRATCHES AND DENT ON POLARIZER OR GLASS					
7.	UNEVEN COLOR SPREAD , COLORATION	(1)TO BE DETERMINED BASED UPON THE STANDARD SAMPLE .					
8.	BEZEL APPEARANCE	<ul> <li>(1)BEZEL MAY NOT HAVE RUST ,BE DEFORMED OR HAVE</li> <li>FINGER PRINTS STAINS OF OTHER CONTAMINATION .</li> <li>(2)BEZEL MUST COMPLY WITH JOB SPECIFICATIONS .</li> </ul>					



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9. SOLDERING 9. SOLDER SOLDER WETS 3 SIDES OF TERMINAL, BUT LESS 1/2 1/2 1/2 1/2 1/2 1/2 1/2 1/2 1/2 1/2	(1)NO SOLDERING FOUND ON THE SPECIFIED PLACE (2)INSUFFICENT SOLDER (a)LSI , IC A POOR WETTING OF SOLDER IS BETWEEN LOWER BEND OR "HEEL" OF LEAD AND PAD SOLDER FILLET (b)CHIP COMPONENT · SOLDER IS LESS THAN 50% OF SIDES AND FRONT
	9. SOLDERING 9. SOLDERING 9. SOLDERING 1/2 



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NO.	ITEM		CRITERIA		
9.	SOLDERING	<ul> <li>(3)PARTS AL</li> <li>(a)LSI, IC LEAD W OUTLIN</li> <li>(b)CHIP CO COMPO 50% OF</li> <li>(4)NO UNME ON THE P</li> <li>(5)NO COLD CONNEC</li> <li>(6)NO RESID</li> <li>(7)NO SHOP</li> </ul>	JGMENT VIDTH IS MORE THAN 50% BEY VE OMPONENT OMPONENT ONENT IS OFF CENTER , AND M THE LEADS IS OFF THE PAD O THE LEADS IS OFF THE PAD O CLIED SOLDER PASTE MAY BE CB. SOLDER JOINTS , MISSING SOI TIONS, OXIDATION OR ICICLE. UE OR SOLDER BALLS ON PCE TO CLIES IN COMPONENTS OF	OND PAE	) N
10.	BACKLIGHT	(1)NO LIGHT (2)FLICKERI (3)SPOTS OR MUST BE CONTAM (4)BACKLIG	I COMPOSITOR AND OTHER ABNORMAL II NG AND OTHER ABNORMAL II SCRATCHES THAT APPEAR W JUDGED USING LCD SPOT , LIN INATION STANDARDS. HT DOESN'T LIGHT OR COLOR	LUMINA HEN LIT NES AND	TION G.



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NO.	ITEM	CRITERIA
		(1)COB SEAL MAY NOT HAVE PINHOLES LARGER THAN
		0.2mm OR CONTAMINATION.
		(2)COB SEAL SURFACE MAY NOT HAVE PINHOLES
		THROUGH TO THE IC.
		(3)THE HEIGHT OF THE COB SHOULD NOT EXCEED THE
		HEIGHT INDICATED IN THE ASSEMBLY DIAGRAM.
		(4)THERE MAY NOT BE MORE THAN 2mm OF SEALANT
		OUTSIDE THE SEAL AREA ON THE PCB, AND THERE
		SHOULD BE NO MORE THAN THREE PLACES.
11.	PCB, COB	(5)NO OXIDATION OR CONTAMINATION PCB TERMINALS
		(6)PARTS ON PCB MUST BE THE SAME AS ON THE
		PRODUCTION CHARACTERISTIC CHART.
		THERE SHOULD BE NO WRONG PARTS, MISSING
		PARTS OR EXCESS PARTS .
		(7)THE JUMPER ON THE PCB SHOULD CONFORM TO THE
		PRODUCT CHARACTERISTIC CHART.
		(8)IF SOLDER GETS ON BEZEL TAB PADS,LED PAD,
		ZEBRA PAD OR SCREW HOLD PAD, MAKE SURE IT IS
		SMOOTHED DOWN .
	GENERAL APPEARANCE	(1)NO OXIDATION, CONTAMINATION, CURVES OR, BENDS
		ON INTERFACE PIN (OLB) OF TCP.
		(2)NO CRACKS ON INTERFACE PIN (OLB) OF TCP.
		(3)NO CONTAMINATION, SOLDER RESIDUE OR SOLDER
		BALLS ON PRODUCT.
		(4)THE IC ON THE TCP MAY NOT BE DAMAGED, CIRCUITS.
		(5)THE UPPERMOST EDGE OF THE PROTECTIVE STRIP ON
		THE INTERFACE PIN MUST BE PRESENT OR LOOK AS
		IF IT CAUSE THE INTERFACE PIN TO SEVER.
		(6)THE RESIDUAL ROSIN OR TIN OIL OF SOLDERING
		(COMPONENT OR CHIP COMPONENT) IS NOT BURNED
12.		INTO BROWN OR BLACK COLOR.
		(7)SEALANT ON TOP OF THE ITO CIRCUIT HAS NOT
		HARDENED.
		(8)PIN TYPE MUST MATCH TYPE IN SPECIFICATION
		SHEET.
		(9)LCD PIN LOOSE OR MISSING PINS.
		(10)PRODUCT PACKAGING MUST THE SAME AS
		SPECIFIED ON PACKAGING SPECIFICATION SHEET.
		(11)PRODUCT DIMENSION AND STRUCTURE MUST
		CONFORM TO PRODUCT SPECIFICATION SHEET.
		(12)THE APPEARANCE OF HEAT SEAL SHOULD NOT
		ADMIT ANY DIRT AND BREAK.



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NO.	ITEM		CRITERIA		
		THE LCD WITH EXTENS	IVE CRACK	IS NOT ACCEPT	ΓABLE
		General glass chip :	a	b	с
		- b	< t/2	< VIEWING AREA	< 1/8X
			$\frac{-1}{t/2} > < 2t$	< W/3	$\leq 1/8X$
			$W_{\pm}$		ц 1/0/
			X = I CD S	IDE I ENGTH	111
			t = GLASS	S THICKNESS	
		Corner part :		h	
		Corner part :	a	D	C
13. CRACKED GLASS		$\leq t/2$	< VIEWING AREA	$\leq 1/8X$	
		$> t/2$ , $\leq 2t$	$\leq W/3$	$\leq 1/8X$	
		*W=EFFEC	I IVE SEAL WID	IH	
			X-LCDSII	DE LENGIH	
			I-OLASS	INCKINESS	
		CHIP ON ELECTRODE PAD	a	b	с
			≤t	≤ 0.5mm	≤ 1/8X
			* X=LCD SI	DE WIDTH	
			t=GLASS	THICKNESS	
			а	b	с
			$\leq t$	$\leq 1/8X$	$\leq$ L
			*X=LCD SIE	DE WIDTH	
			t = GLASS	THICKNESS	
			L=ELECTR	ODE PAD LENG	ΤH
		①IF GLASS (	CHIPPING THE IT	0	
		* KOAAA	TERMINA	L, OVER 2/3 OF T	THE ITO
		C A A A A A A A A A A A A A A A A A A A	MUSI KEN	MAIN AND BE , D ACCORDING TO	0
		` <b>` →</b> *'b	ELECTRO	DE TERMINAL	
			SPECIFICA	TIONS	
			<b>©IF THE PRO</b>	DUCT WILL BE	HEAT
			SEALED B	Y THE CUSTOME	ER, THE
			ALIGNME	NT MARK MUST	NOT BE
			DEMAGEL	)	



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### 11.6 RELIABILITY TEST

#### 11.6.1 STANDARD SPECIFICATIONS FOR RELIABILITY OF LCD MODULE

NO	ITEM	DESCRIPTION
1	HIGH TEMPERATURE OPERATION	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +70°C FOR 240 hrs
2	LOW TEMPERATURE OPERATION	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -20°C FOR 240 hrs
3	HIGH TEMPERATURE STORAGE	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +80°c FOR 240 hrs
4	LOW TEMPERATURE STORAGE	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -30°C FOR 240 hrs
5	HIGH TEMPERATURE / HUMIDITY TEST	THE SAMPLE SHOULD BE ALLOWED TO STAND AT 40°C, 90% RH 240 hrs
6	HIGH TEMPERATURE / THE SAMPLE SHOULD BE ALLOWED TO STAND AT 40°C, 90% RH HIGH HUMIDITY STORAGE240 hrs	
7	THERMAL SHOCK ( NOT OPERATED )	THE SAMPLE SHOULD BE ALLOWED TO STAND THE FOLLOWING 10 CYCLES OF OPERATION : -30°C FOR 30 MINUTES +80°C FOR 30 MINUTES
8	ESD ( ELECTROSTATIC DISCHARGE )	AIR DISCHARGE ± 4KV CONTACT DISCHARGE ± 2KV
9	DROP TEST (1BOX)	6 FACES, 2 CORNERS HEIGHT : 750mm



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#### 11.6.2 TESTING CONDITIONS AND INSPECTION CRITERIA

FOR THE FINAL TEST THE TESTING SAMPLE MUST BE STORED AT ROOM TEMPERATURE FOR 24 HOURS, AFTER THE TESTS LISTED IN TABLE 6.2, STANDARD SPECIFICATIONS FOR RELIABILITY HAVE BEEN EXECUTED IN ORDER TO ENSURE STABILITY.

NO	ITEM	TEST MODEL	INSPECTION CRITERIA
1	CURRENT CONSUMPTIO N	REFER TO SPECIFICATION	THE CURRENT CONSUMPTION SHOULD CONFORM TO THE PRODUCT SPECIFICATION.
2	CONTRAST	REFER TO SPECIFICATION	AFTER THE TESTS HAVE BEEN EXECUTED , THE CONTRAST MUST BE LARGER THAN HALF OF ITS INITIAL VALUE PRIOR TO THE TESTS.
3	APPEARANCE	VISUAL INSPECTION	DEFECT FREE

#### 11.6.3 LIFE TIME

LIFE TIME	FUNCTIONS, PERFORMANCE, APPEARANCE, ETC. SHALL BE FREE FROM REMARKABLE DETERIORATION WITHIN 50,000 HOURS UNDER ORDINARY OPERATING AND STORAGE CONDITIONS ROOM TEMPERATURE (25±10°C), NORMAL HUMIDITY (45±20% RH), AND IN AREA NOT EXPOSED TO DIRECT SUN LIGHT. (LIFE TIME OF BACKLIGHT, PLEASE REFER TO DATA ABOUT BACKLIGHT.)
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NOTE : FROM OUR EXPERIENCE THE LIFE TIME OF HIGH HUMIDITY OPERATION AND HIGH TEMPERATURE OPERATION AS ABOVE MENTIONED COULD BE ACHIEVED.



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# 11.7 OPERATION

- 11.7.1 Do not connect or disconnect modules to or from the main system while power is being supplied .
- 11.7.2 Use the module within specified temperature ; lower temperature causes the retardation of blinking speed of the display ; higher temperature makes overall display discolor . When the temperature returns to normality , the display will operate normally .
- 11.7.3 Adjust the LC driving voltage to obtain the optimum contrast .
- 11.7.4 Power On Sequence input signals should not be supplied to LCD module before power supply voltage is applied and reaches the specified value ( $5 \pm 0.25v$ ).

If above sequence is not followed, CMOS LSIs of LCD modules may be damaged due to latch - up problem .

#### 11.8 NOTICE

- 11.8.1 Use a grounded soldering iron when soldering connector I/O terminals . For soldering or repairing , take precaution against the temperature of the soldering iron and the soldering time to prevent peeling off the through-hole-pad .
- 11.8.2 Do not disassemble . EDT shall not be held responsible if the module is disassembled and upon the reassembly the module failed .
- 11.8.3 Do not charge static electricity, as the circuit of this module contains CMOS LSIs. A workman's body should always be static-protected by use of an ESD STRAP. Working clothes for such personnel should be of static-protected material.
- 11.8.4 Always ground the electrically-powered driver before using it to install the LCD module . While cleaning the work station by vacuum cleaner , do not bring the sucking mouth near the module ; static electricity of the electrically-powered driver or the vacuum cleaner may destroy the module .
- 11.8.5 Don't give external shock.
- 11.8.6 Don't apply excessive force on the surface.
- 11.8.7 Liquid in LCD is hazardous substance .Must not lick and swallow. When the liquid is attach to your,skin,cloth etc.wash it out thoroughly and immediately.
- 11.8.8 Don't operate it above the absolute maximum rating.
- 11.8.9 Storage in a clean environment , free from dust, active gas, and solvent.
- 11.8.10 Store without any physical load.
- 11.8.11 Rewiring : no more than 3 times .